

WPM2341A

P-Channel Enhancement Mode Mosfet

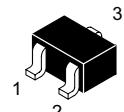
[Http://www.sh-willsemi.com](http://www.sh-willsemi.com)

Features

- Higher Efficiency Extending Battery Life
- Miniature SOT23-3 Surface Mount Package
- Super high density cell design for extremely low RDS (ON)

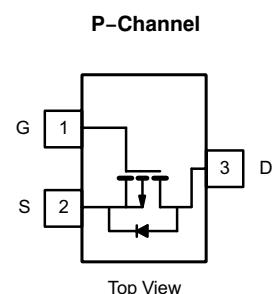
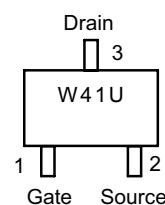
Applications

- DC/DC Converter
- Load Switch
- Battery Powered System
- LCD Display inverter
- Power Management in Portable, Battery Powered Products


SOT 23-3
pin connections :

ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ\text{C}$, unless otherwise noted					
Parameter		Symbol	5 s	Steady State	Unit
Drain-Source Voltage		V_{DS}	-20		V
Gate-Source Voltage		V_{GS}	± 12		
Continuous Drain Current	$T_A=25^\circ\text{C}$	I_D	-4.3	-3.5	A
($T_J = 150^\circ\text{C}$) ^a	$T_A=80^\circ\text{C}$		-3.2	-2.5	
Pulsed Drain Current		I_{DM}	-20		
Continuous Source Current (Diode Conduction) ^a		I_S	-1.7	-1	
Maximum Power	$T_A=25^\circ\text{C}$	P_D	1.25	0.75	W
Dissipation ^a	$T_A=80^\circ\text{C}$		0.7	0.42	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to 150		°C

a. Surface Mounted on FR4 Board using 1 in sq pad size, 2oz Cu.


Marking:


W 41= Specific Device Code
U = Date Code

Order information

Part Number	Package	Shipping
WPM2341A-3/TR	SOT23-3	3000 Tape & Reel

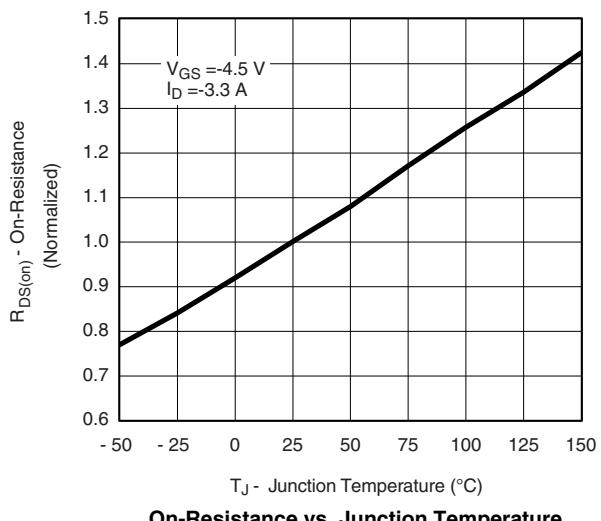
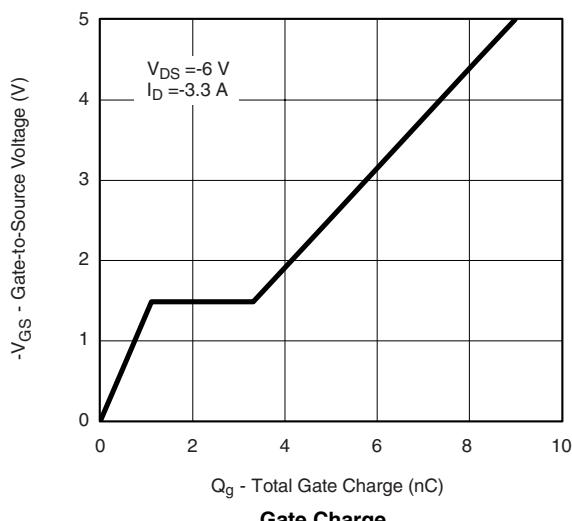
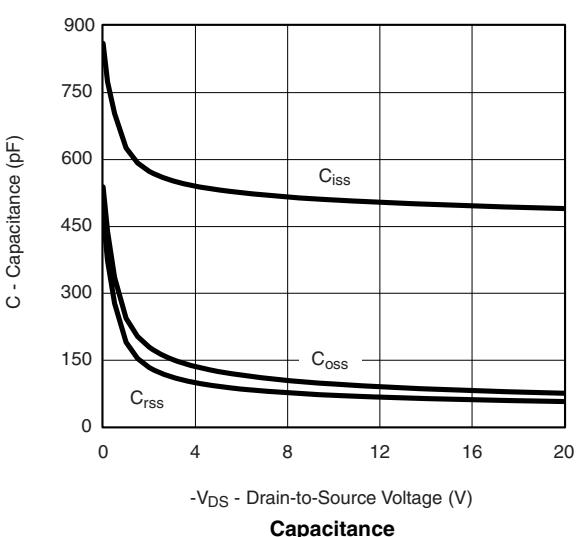
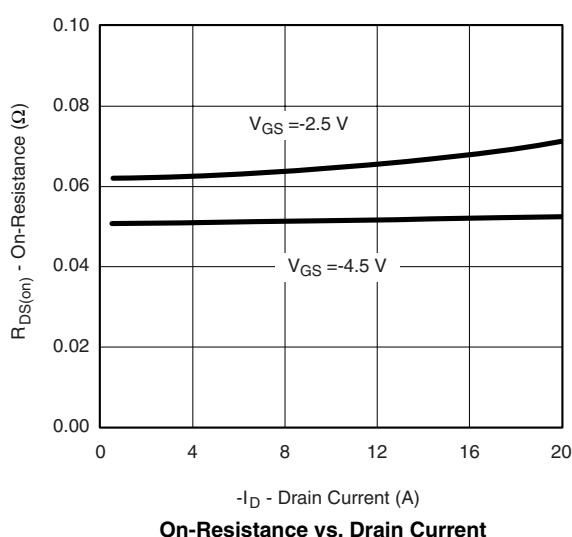
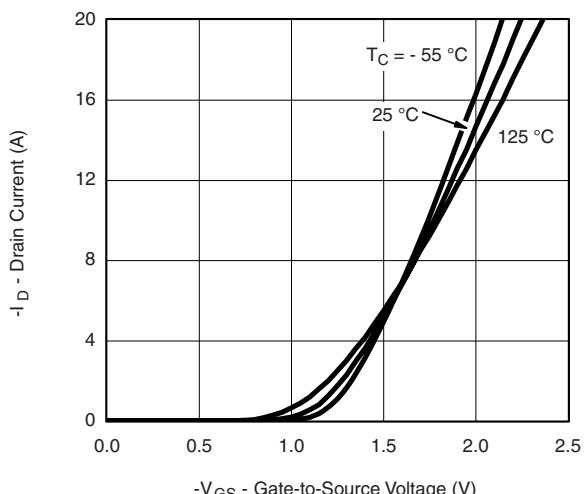
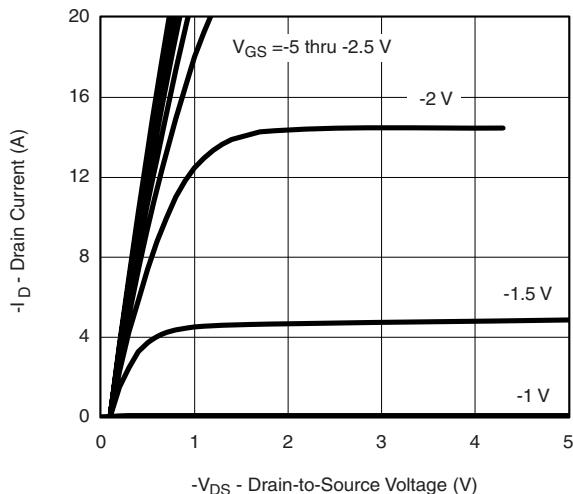
THERMAL RESISTANCE RATINGS

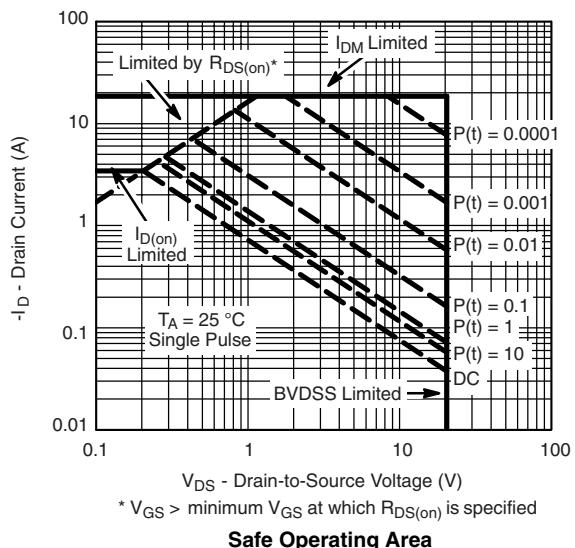
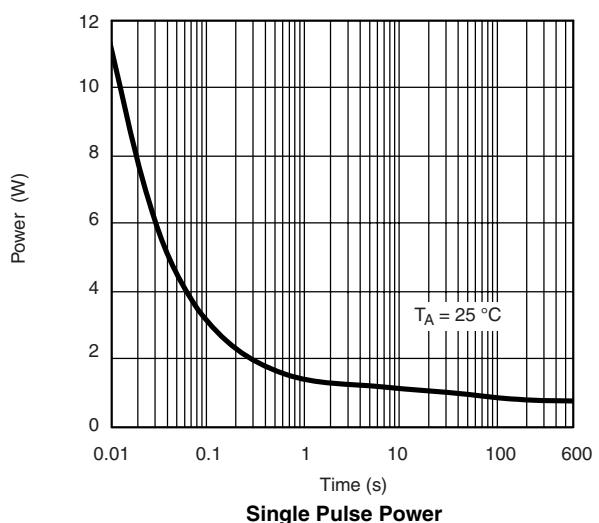
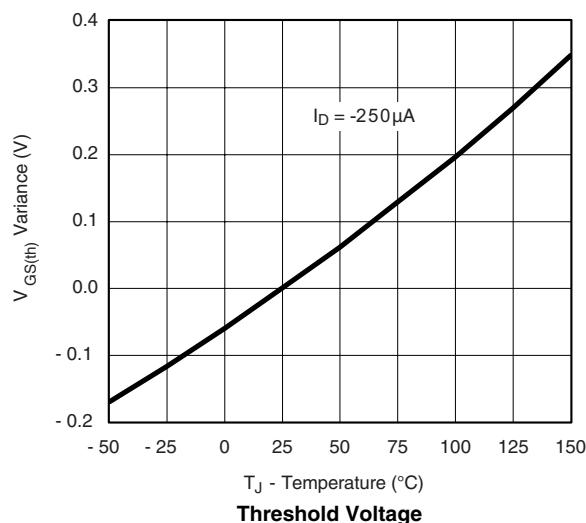
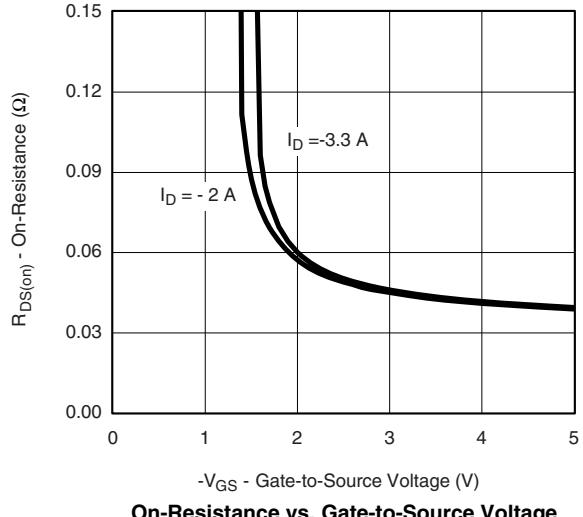
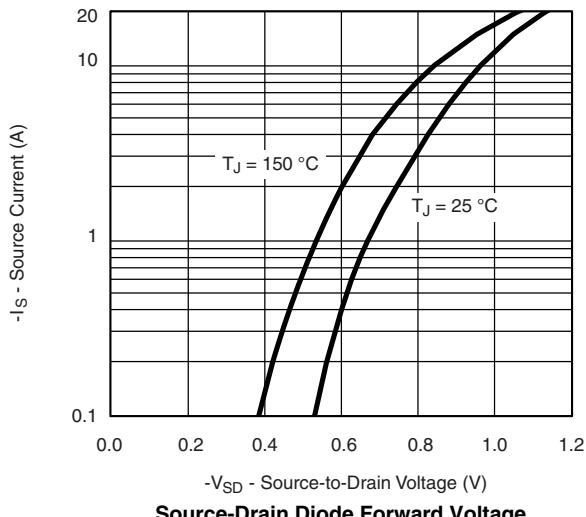
Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance ^b	$t \leq 5 \text{ s}$	$R_{\theta JA}$	75	100	$^{\circ}\text{C/W}$
	Steady State		125	165	

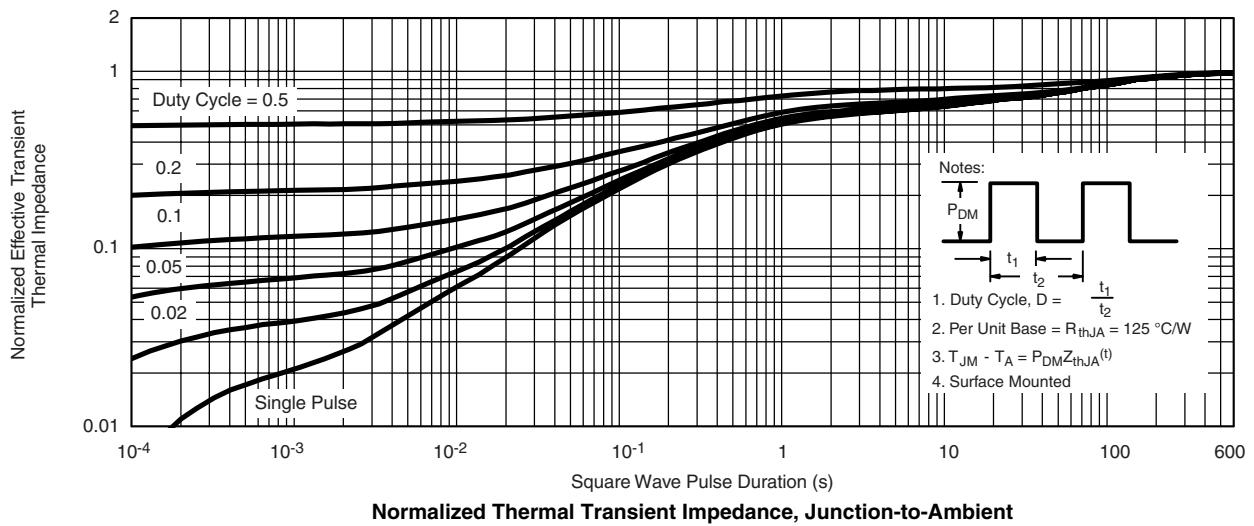
b. Surface Mounted on FR4 Board using 1 in sq pad size, 2oz Cu.

MOSFET ELECTRICAL CHARACTERISTICS($T_J = 25 \text{ }^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -16\text{V}, V_{GS} = 0\text{V}$			-1	μA
Gate-Source leakage current	I_{GSS}	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0\text{V}$			± 100	nA
On Characteristics						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{GS} = V_{DS}, I_D = -250\mu\text{A}$	-0.35	-0.63	-1.00	V
Static Drain-Source On-Resistance	$R_{DS(\text{on})}$	$V_{GS} = -4.5\text{V}, I_D = -3.3\text{A}$		52	61	$\text{m}\Omega$
		$V_{GS} = -2.5\text{V}, I_D = -2.8 \text{ A}$		65	71	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{DS} = -5 \text{ V}, I_D = -3.3\text{A}$		3.0		S
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS} = -6 \text{ V}, V_{GS} = 0\text{V}, f = 1.0 \text{ MHz}$			700	pF
Output Capacitance	C_{oss}				160	pF
Reverse Transfer Capacitance	C_{rss}				120	pF
Switching Characteristics						
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = -4.5\text{V}, V_{DD} = -6 \text{ V}, I_D = -1.0\text{A}, R_G = 6.0\Omega$			25	ns
Turn-On Rise Time	t_r				55	ns
Turn-Off Delay Time	$t_{d(off)}$				90	ns
Turn-Off Fall Time	t_f				60	ns
Total Gate Charge	$Q_{G(TOT)}$	$V_{DS} = -6 \text{ V}, I_D = -3.3\text{A}, V_{GS} = -4.5\text{V}$		8	13	nC
Threshold gate charge	$Q_{G(TH)}$			0.2		nC
Gate-Source Charge	Q_{GS}			1.2		nC
Gate-Drain Charge	Q_{GD}			2.2		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Forward Diode Voltage	V_{SD}	$V_{GS} = 0\text{V}, I_S = -1.6\text{A}$		-0.8		V

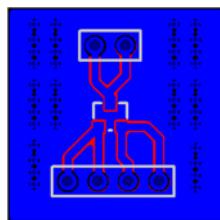
Typical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise noted)


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Power Dissipation Characteristics

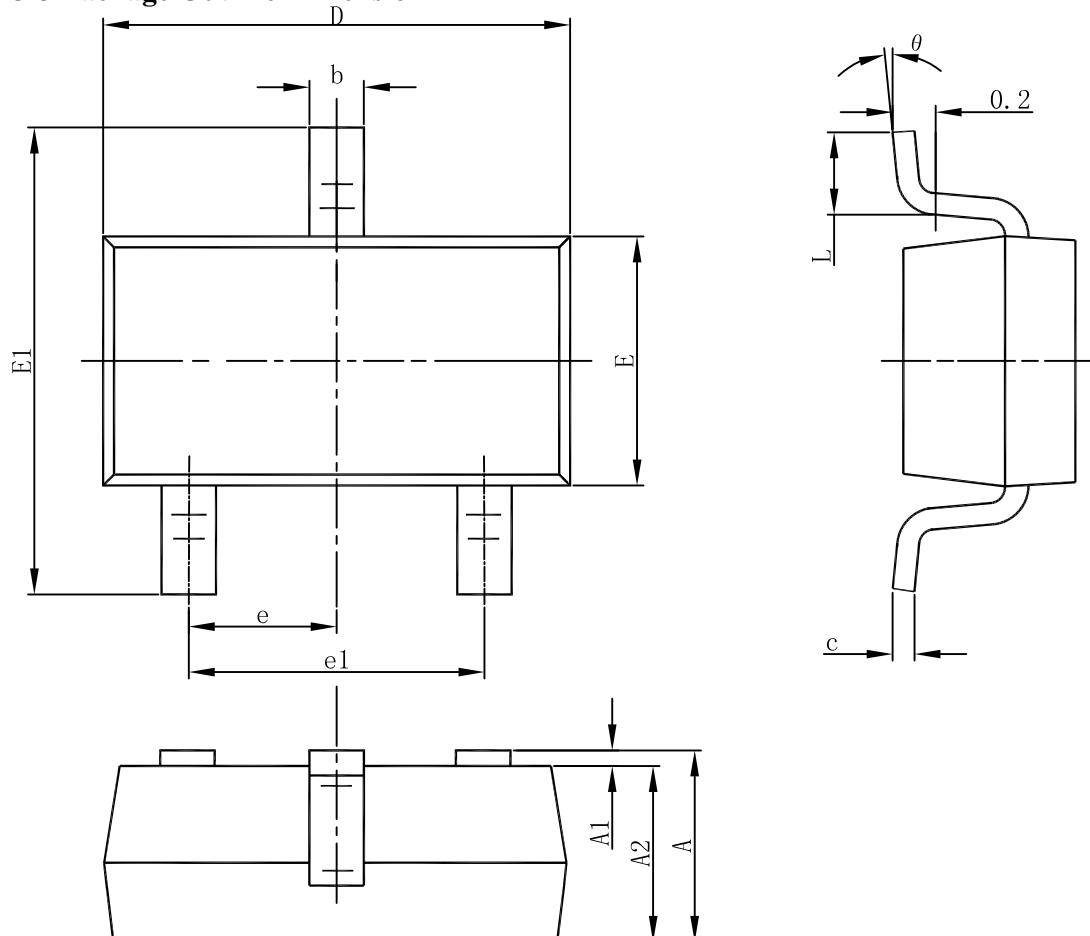
1. The package of WPM2341A is SOT23-3, surface mounted on FR4 Board using 1 in sq pad size, 2 oz Cu, $R_{\theta JA}$ is 125 °C/W.
2. The power dissipation P_D is based on $T_{J(MAX)}=150^{\circ}\text{C}$, and the relation between T_J and P_D is $T_J = T_a + R_{\theta JA} * P_D$, the maximum power dissipation is determined by $R_{\theta JA}$.
3. The $R_{\theta JA}$ is the thermal impedance from junction to ambient, using larger PCB pad size can get smaller $R_{\theta JA}$ and result in larger maximum power dissipation.



125 °C/W when mounted on
a 1 in² pad of 2 oz copper.

Packaging Information

SOT23-3 Package Outline Dimension



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°